

Title (en)

METHOD FOR THE PRODUCTION OF A RIGID POWER MODULE

Title (de)

VERFAHREN ZUM HERSTELLEN EINES FESTEN LEISTUNGSMODULS

Title (fr)

METHODE DE FABRICATION D'UN MODULE DE PUISSANCE RIGIDE

Publication

EP 2143140 A2 20100113 (DE)

Application

EP 08748729 A 20080402

Priority

- DE 2008000566 W 20080402
- DE 102007020618 A 20070430

Abstract (en)

[origin: WO2008131713A2] Disclosed is a method for producing a rigid power module, comprising the following steps: a monolithic lead frame is produced; said lead frame is equipped with semiconductor components and optional passive components, and corresponding connections are bonded; the equipped lead frame is introduced into a pressing tool such that the uncovered lead frame is accessible; the lead frame is fastened within the tool by means of a mounting die; and a duroplastic compression molding material is pressed into the tool so as to envelop the equipped lead frame. Said method is characterized in that cavities are left in predetermined positions in the envelope of the power module during the enveloping process. Furthermore, webs of the monolithic lead frame are cut out by means of punches that are introduced into the cavities such that electrically insulated islands of materials of the previously monolithic lead frame are created.

IPC 8 full level

H01L 23/495 (2006.01); **H01L 21/48** (2006.01); **H01L 21/56** (2006.01)

CPC (source: EP)

H01L 21/565 (2013.01); **H01L 23/49541** (2013.01); **H01L 23/49575** (2013.01); **H01L 23/4006** (2013.01); **H01L 24/49** (2013.01); **H01L 2224/49175** (2013.01); **H01L 2924/00014** (2013.01); **H01L 2924/01019** (2013.01); **H01L 2924/01068** (2013.01); **H01L 2924/13055** (2013.01); **H01L 2924/15747** (2013.01); **H01L 2924/181** (2013.01)

Citation (search report)

See references of WO 2008131713A2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)

DE 102007020618 B3 20081030; **DE 102007020618 B8 20090312**; CN 101689538 A 20100331; CN 101689538 B 20120808; EP 2143140 A2 20100113; EP 2261971 A1 20101215; WO 2008131713 A2 20081106; WO 2008131713 A3 20081231

DOCDB simple family (application)

DE 102007020618 A 20070430; CN 200880014260 A 20080402; DE 2008000566 W 20080402; EP 08748729 A 20080402; EP 10008598 A 20080402